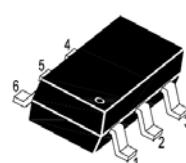
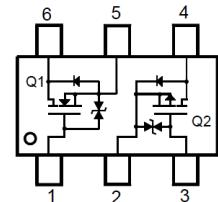


Main Product Characteristics

Polarity	N-Ch	P-Ch
V_{DSS}	60V	-60V
$R_{DS(ON)}$	4Ω (Max.)	7Ω (Max.)
I_D	0.5A	-0.35A


SOT-23-6L

Schematic Diagram


Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery

Description

The GSFR0600 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value		Unit
		N-Channel	P-Channel	
Drain-Source Voltage	V_{DS}	60	-60	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Drain Current-Continuous	I_D	500	-350	mA
Drain Current-Pulsed ¹	I_{DM}	1.5	-1	A
Power Dissipation ²	P_D	900		mW
Operating Junction Temperature Range	T_J	-55 To +150		°C
Storage Temperature Range	T_{STG}	-55 To +150		°C
Thermal Resistance Junction to Ambient ²	$R_{\theta JA}$	139		°C/W

Note:

1. Pulse test: pulse width $\leq 100\mu\text{s}$, duty cycle $\leq 2\%$. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$.
2. Device mounted on FR-4 substrate PC board, 2oz copper, with 1 inch square copper plate in still air.

N-Channel Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$I_D=250\mu\text{A}$	60	-	-	V
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 16\text{V}$	-	-	± 10	μA
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=48\text{V}$	-	-	1	μA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	0.8	-	2.5	V
Static Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_D=500\text{mA}$	-	-	3	Ω
		$V_{\text{GS}}=4.5\text{V}, I_D=200\text{mA}$	-	-	4	
Forward Transconductance	g_{FS}	$V_{\text{DS}}=10\text{V}, I_D=200\text{mA}$	-	265	-	mS
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	200	-	Ω
Dynamic and Switching Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	22.5	-	pF
Output Capacitance	C_{oss}		-	12	-	
Reverse Transfer Capacitance	C_{rss}		-	0.5	-	
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{\text{DS}}=30\text{V}, I_D=0.5\text{A}, V_{\text{GS}}=10\text{V}, R_G=25\Omega$	-	2.7	-	nS
Turn-On Rise Time	t_r		-	2.5	-	
Turn-Off Delay Time	$t_{d(\text{off})}$		-	13	-	
Turn-Off Fall Time	t_f		-	8	-	
Gate Charge Total	Q_g	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=4.5\text{V}, I_D=0.5\text{A}$	-	0.44	-	nC
Gate to Source Charge	Q_{gs}		-	0.2	-	
Gate to Drain Charge	Q_{gd}		-	0.1	-	
Body-Diode Parameters						
Drain-Source Diode Forward Voltage	V_{SD}	$I_S=0.5\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.2	V
Body-Diode Continuous Current	I_S	-	-	-	500	mA
Body Diode Reverse Recovery Time	t_{rr}	$I_S=0.5\text{A}, \text{di}/\text{dt}=100\text{A}/\mu\text{s}$	-	30	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_S=0.5\text{A}, \text{di}/\text{dt}=100\text{A}/\mu\text{s}$	-	29	-	nC

P-Channel Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$I_D=-250\mu\text{A}$	-60	-	-	V
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 16\text{V}$	-	-	± 10	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-48\text{V}$	-	-	-1	μA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=-250\mu\text{A}$	-0.8	-	-2.5	V
Static Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_D=-500\text{mA}$	-	-	5	Ω
		$V_{\text{GS}}=-4.5\text{V}, I_D=-200\text{mA}$	-	-	7	
Dynamic and Switching Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	38	-	pF
Output Capacitance	C_{oss}		-	9	-	
Reverse Transfer Capacitance	C_{rss}		-	6	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-25\text{V}, I_D=-0.1\text{A}, V_{\text{GS}}=-10\text{V}, R_G=6.8\Omega$	-	14	-	nS
Turn-On Rise Time	t_r		-	4	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	15	-	
Turn-Off Fall Time	t_f		-	77	-	
Gate Charge Total	Q_g	$V_{\text{DS}}=-25\text{V}, V_{\text{GS}}=-4.5\text{V}, I_D=-0.1\text{A}$	-	1.1	-	nC
Gate to Source Charge	Q_{gs}		-	0.3	-	
Gate to Drain Charge	Q_{gd}		-	0.2	-	
Body-Diode Parameters						
Body Diode Voltage	V_{SD}	$I_S=-500\text{mA}$	-	-	-1.2	V
Body-Diode Continuous Current	I_S	-	-	-	-350	mA
Body Diode Reverse Recovery Time	t_{rr}	$I_S=-0.1\text{A}, \frac{di}{dt}=100\text{A}/\mu\text{s}$	-	60	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_S=-0.1\text{A}, \frac{di}{dt}=100\text{A}/\mu\text{s}$	-	58	-	nC

Typical Electrical and Thermal Characteristic Curves (N-Channel)

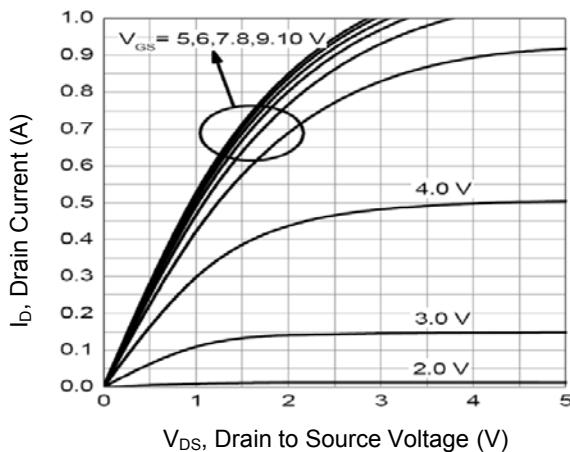


Figure 1. Typical Output Characteristics

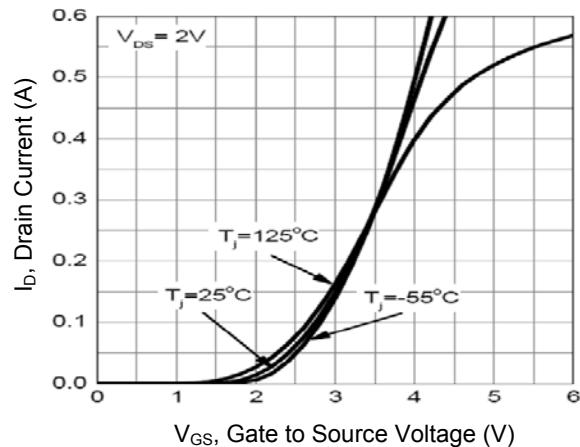


Figure 2. Typical Transfer Characteristics

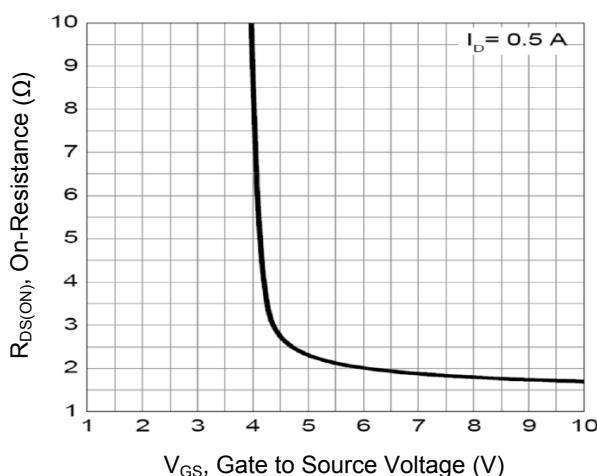


Figure 3. Gate to Source Voltage vs. $R_{DS(on)}$

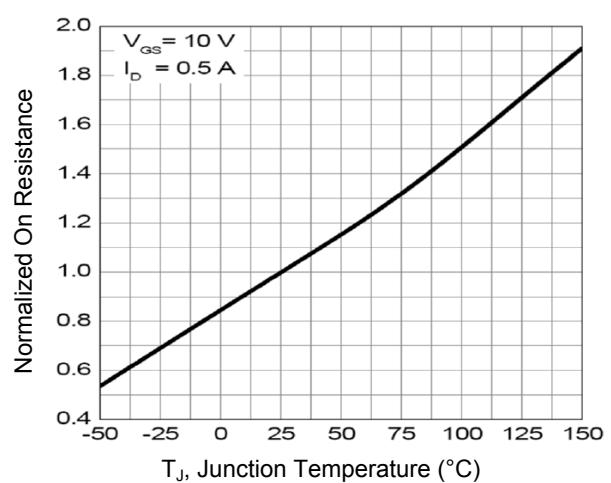


Figure 4. On-Resistance vs. T_J

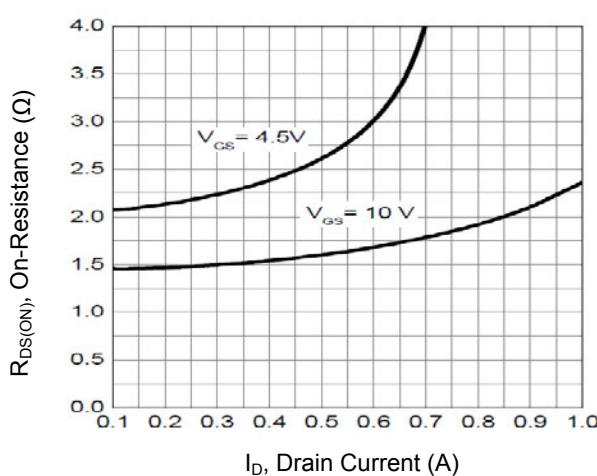


Figure 5. On Resistance vs. Drain Current

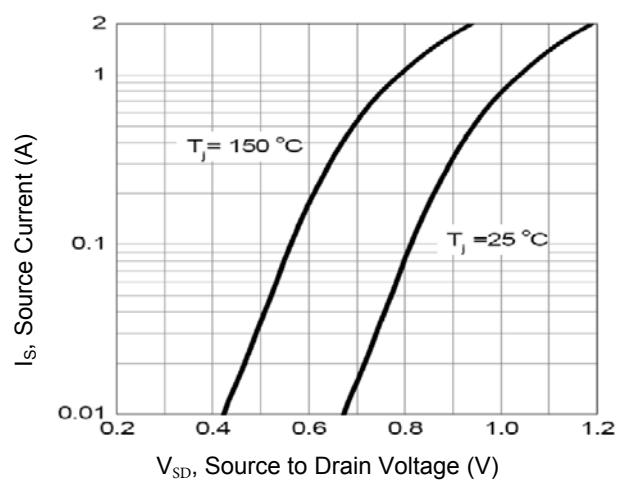


Figure 6. Typical Forward Characteristics

Typical Electrical and Thermal Characteristic Curves (N-Channel)

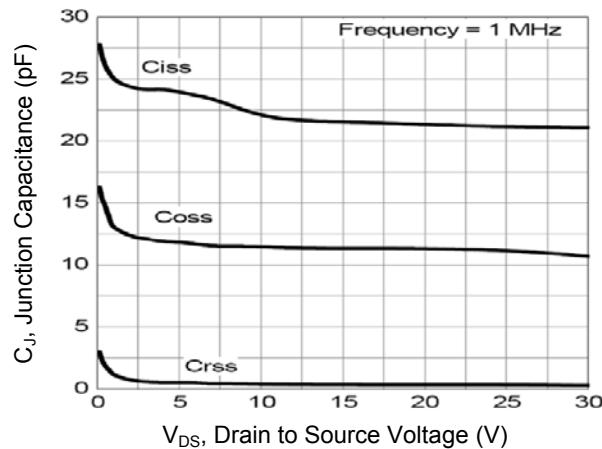


Figure 7. Typical Junction Capacitance

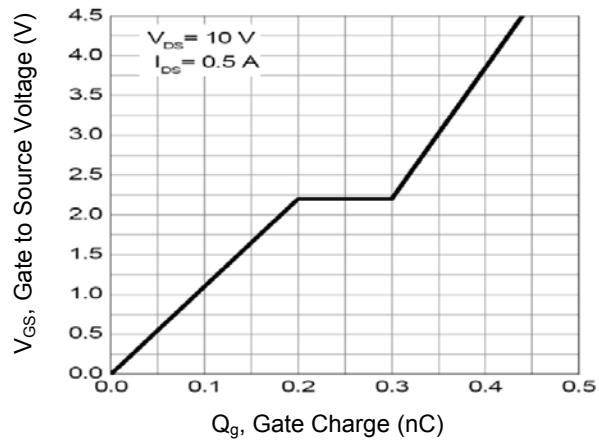


Figure 8. Gate Charge

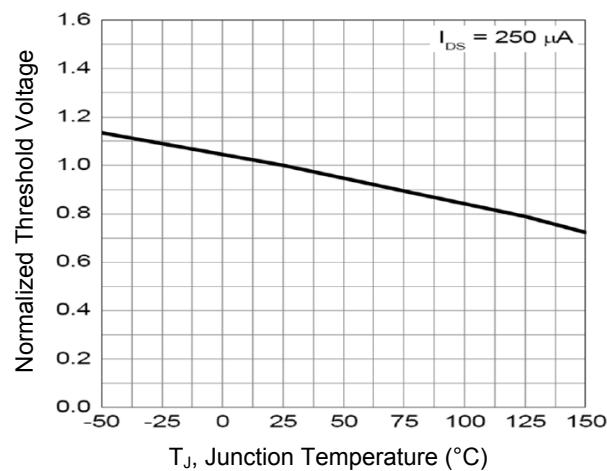


Figure 9. Gate Threshold Variation vs. T_J

Typical Electrical and Thermal Characteristic Curves (P-Channel)

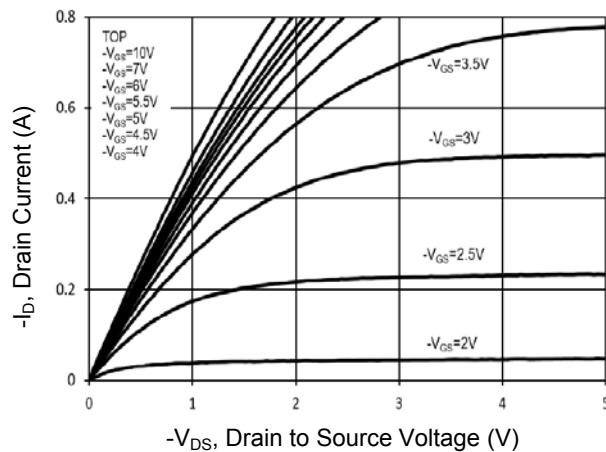


Figure 1. Output Characteristics

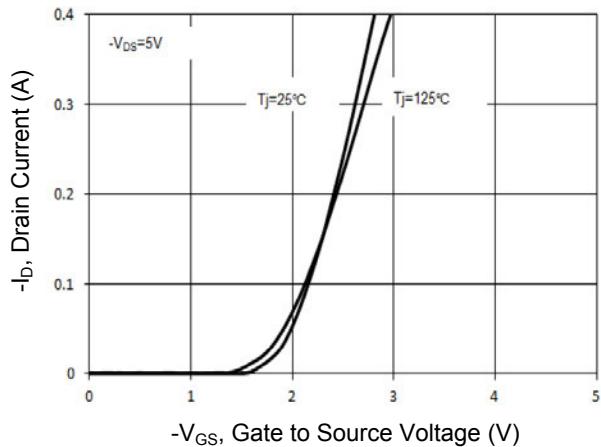


Figure 2. Transfer Characteristics

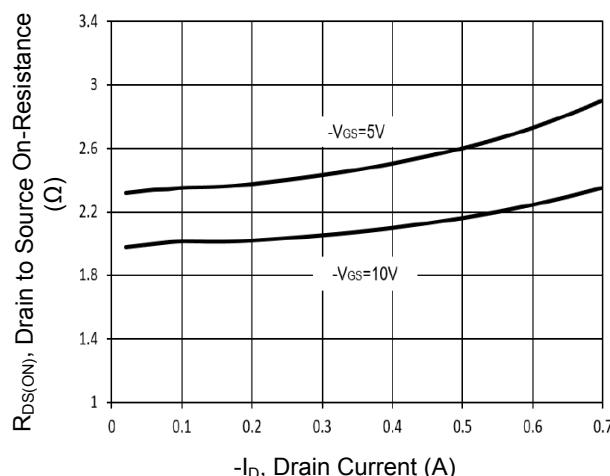


Figure 3. On-Resistance vs. Drain Current

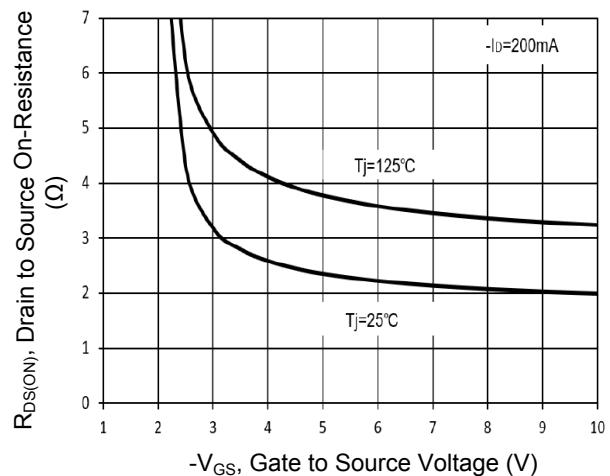


Figure 4. On-Resistance vs. Gate to Source Voltage

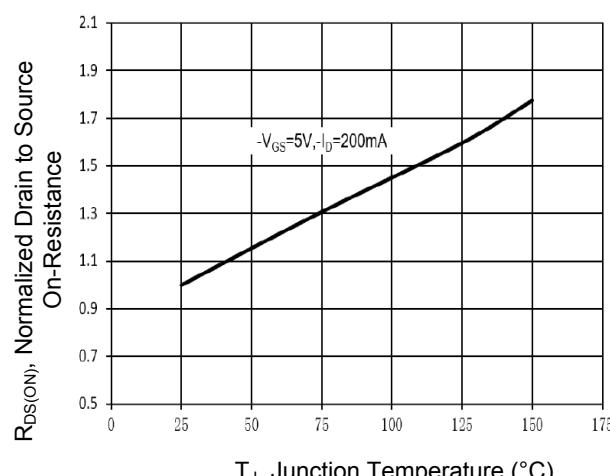


Figure 5. On Resistance vs. T_j

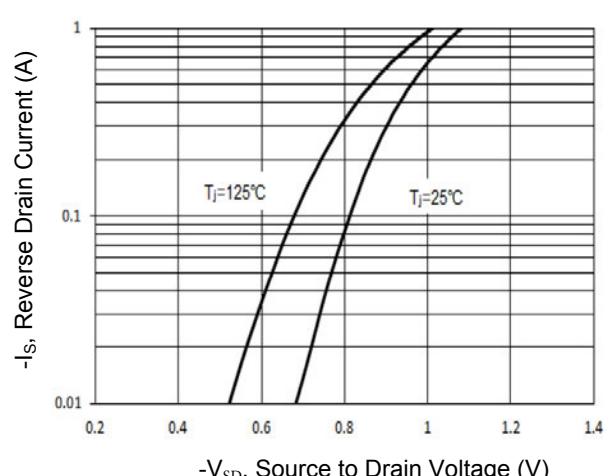


Figure 6. Typical Body Diode Forward Characteristics

Typical Electrical and Thermal Characteristic Curves (P-Channel)

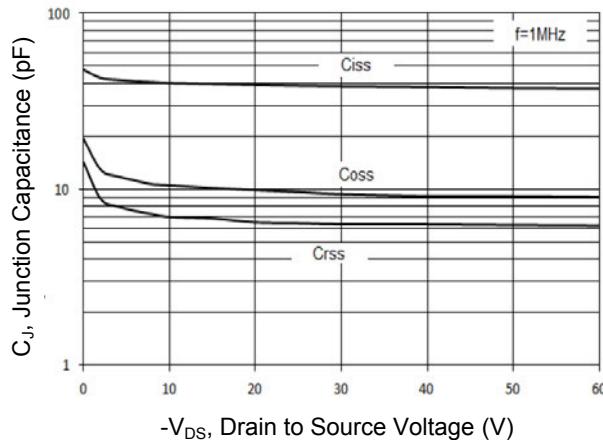


Figure 7. Capacitance Characteristics

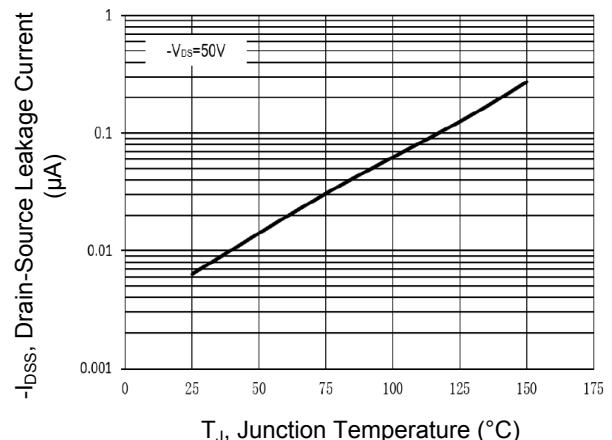


Figure 8. Drain to Source Leakage Current vs. T_J

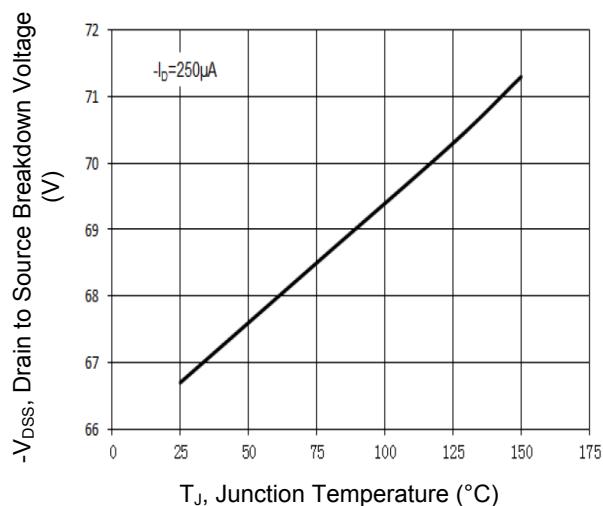


Figure 9. $V_{(BR)DSS}$ vs. Junction Temperature

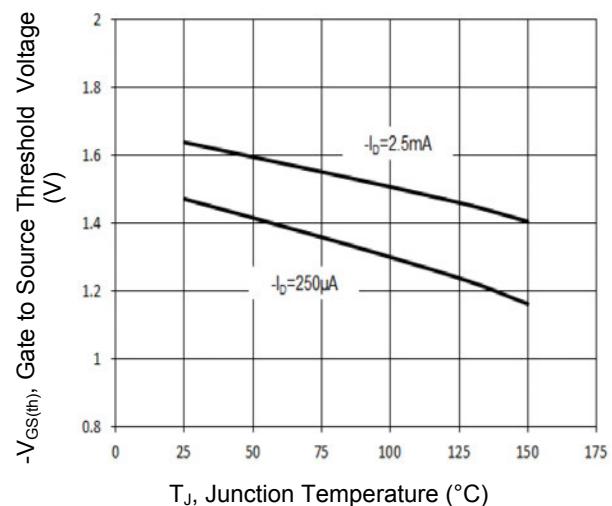


Figure 10. Gate to Source Threshold Voltage vs. T_J

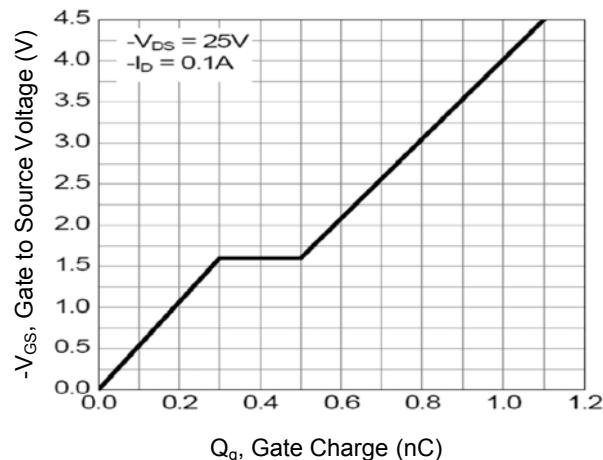
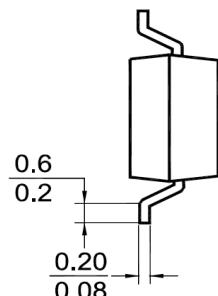
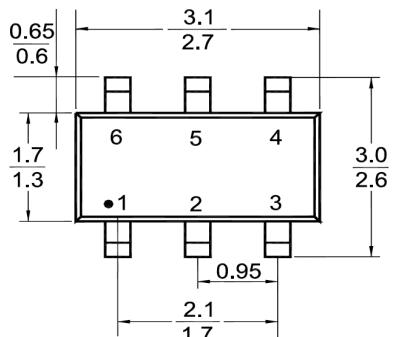
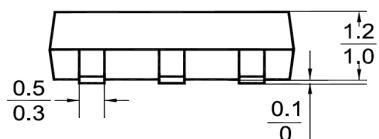


Figure 11. Gate Charge

Package Outline Dimensions (SOT-23-6L)

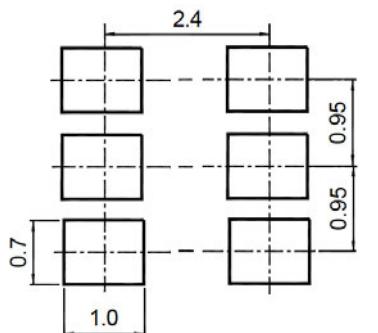


Unit: mm



Unit: mm

Recommended Pad Layout



Unit: mm

Order Information

Device	Package	Marking	Carrier	Quantity
GSFR0600	SOT-23-6L	QF	Tape & Reel	3,000pcs / Reel